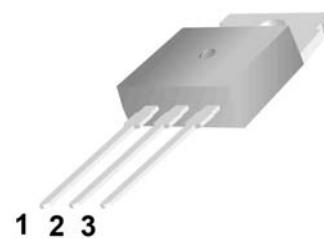


**●Features:**

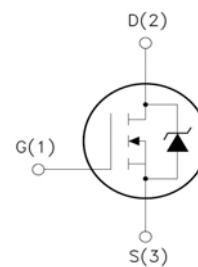
- 2.0A, 650V,  $R_{DS(on)(Typ)} = 4.2\Omega$  @  $V_{GS} = 10V$
- Low Gate Charge
- Low  $C_{rss}$
- 100% Avalanche Tested
- Fast Switching
- Improved dv/dt Capability

**●Application:**

- High Frequency Switching Mode Power Supply
- Active Power Factor Correction



TO-220



1.Gate (G)  
 2.Drain (D)  
 3.Source (S)

**Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	650	V
$I_D$	Drain Current - Continuous (T <sub>c</sub> =25°C)	2.0*	A
	- Continuous (T <sub>c</sub> =100°C)	1.3*	A
$I_{DM}$	Drain Current - Pulsed (Note1)	8*	A
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note2)	120	mJ
$I_{AR}$	Avalanche Current (Note1)	2.0	A
$E_{AR}$	Repetitive Avalanche Energy (Note1)	4.4	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ (Note3)	4.5	V/ns
$P_D$	Power Dissipation (T <sub>c</sub> =25°C)	23	W
	-Derate above 25°C	0.18	W/°C
$T_j$	Operating Junction Temperature	150	°C
$T_{stg}$	Storage Temperature Range	-55 to +150	°C

\* Drain Current Limited by Maximum Junction Temperature.

**Thermal Characteristics**

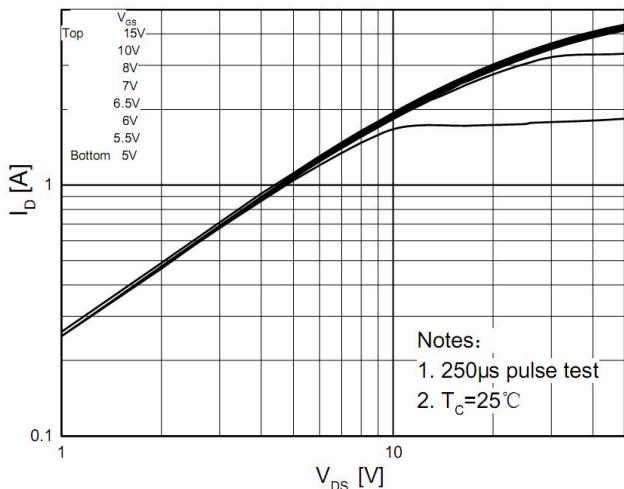
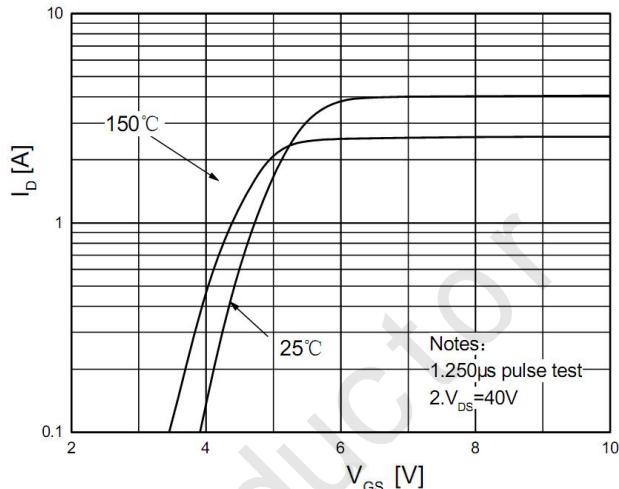
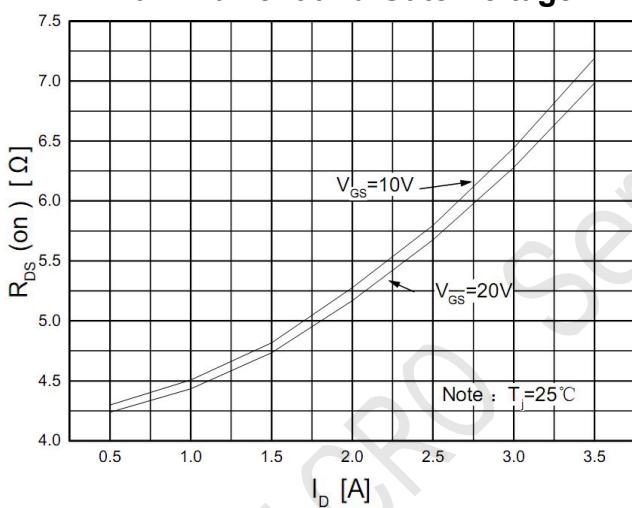
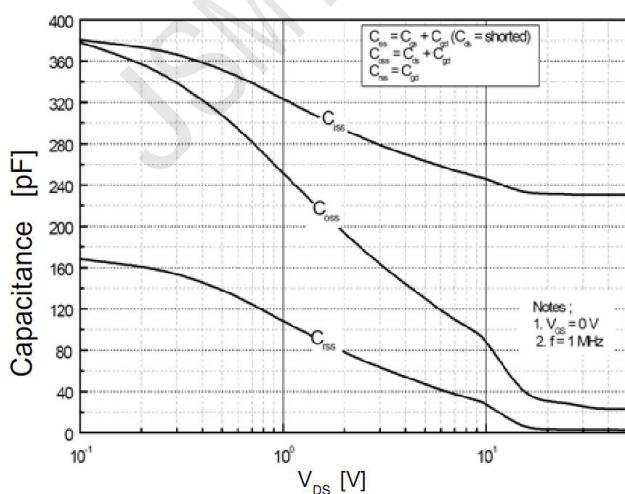
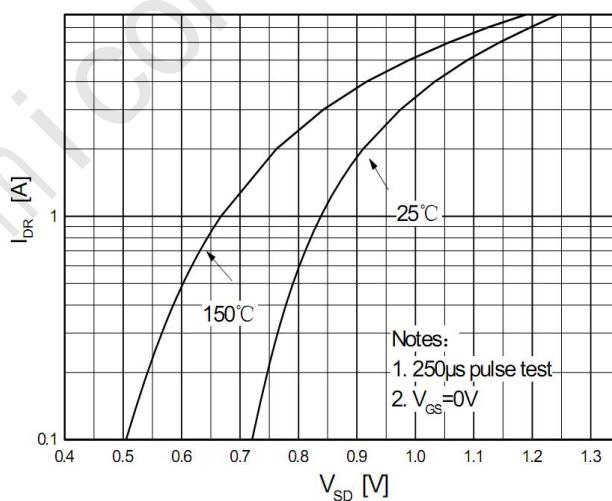
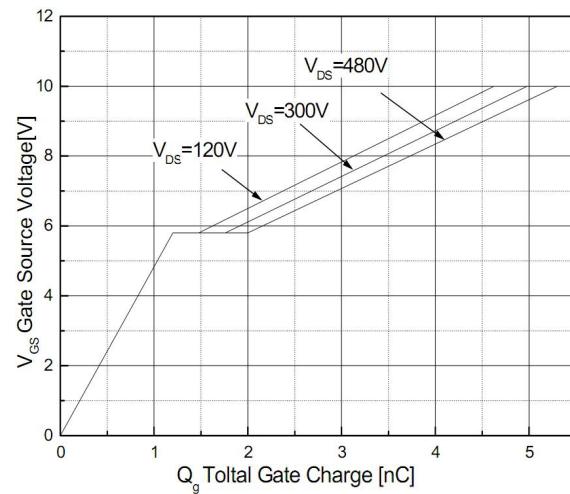
Symbol	Parameter	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	5.5	°C /W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	°C /W

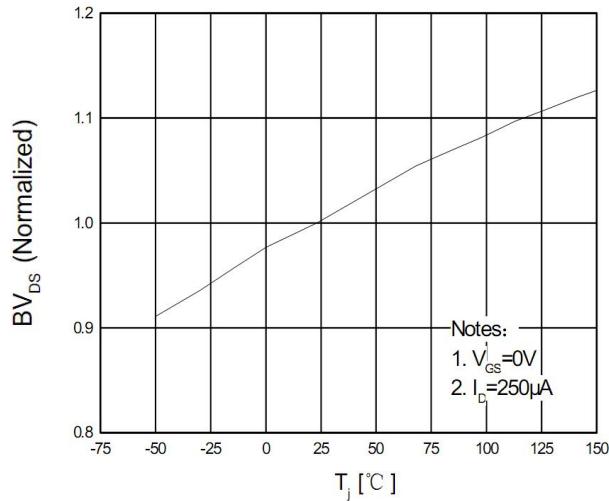
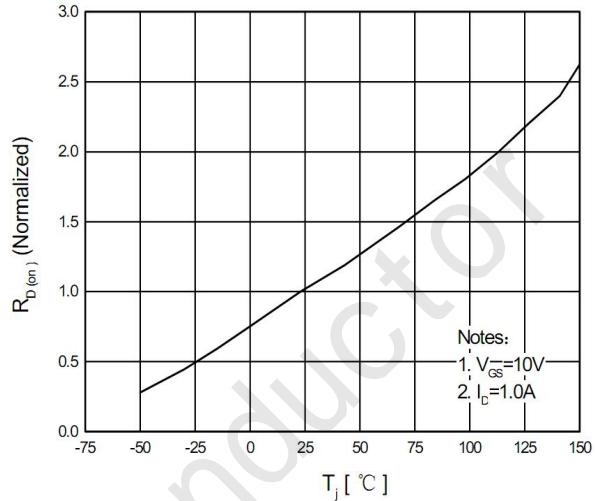
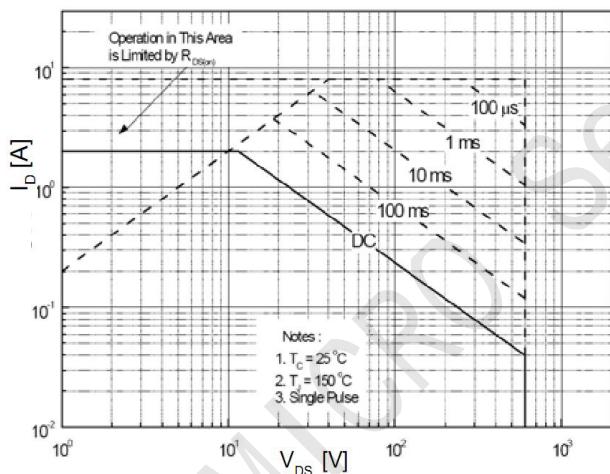
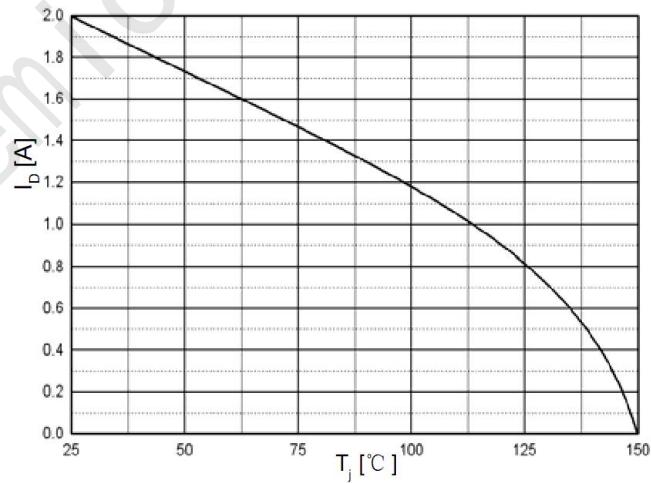
**Electrical Characteristics(Tc=25°C unless otherwise noted)**

Symbol	Parameter	Test Conditons	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	650	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D=250\mu A$ (Referenced to 25°C)	--	0.65	--	V/°C
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=650V, V_{GS}=0V$	--	--	1	$\mu A$
		$V_{DS}=520V, T_c=125^{\circ}C$	--	--	10	$\mu A$
$I_{GSSF}$	Gate-Body Leakage Current,Forward	$V_{GS}=+30V, V_{DS}=0V$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current,Reverse	$V_{GS}=-30V, V_{DS}=0V$	--	--	-100	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0	--	4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=1.0A$	--	4.2	4.9	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS}=40V, I_D=1.0A$ (Note4)	--	1.9	--	S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1.0MHz$	--	270	--	pF
$C_{oss}$	Output Capacitance		--	40	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	5	--	pF
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 325V, I_D = 2.0A, R_G = 25\Omega$ (Note4,5)	--	7	--	ns
$t_r$	Turn-On Rise Time		--	23	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	2	--	ns
$t_f$	Turn-Off Fall Time		--	24	--	ns
$Q_g$	Total Gate Charge	$V_{DS} = 520V, I_D = 2.0A, V_{GS} = 10V$ (Note4,5)	--	9	--	nC
$Q_{gs}$	Gate-Source Charge		--	1.6	--	nC
$Q_{gd}$	Gate-Drain Charge		--	4.3	--	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain-Source Diode Forward Current	--	--	2.0	--	A
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current	--	--	8	--	A
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_S = 2.0A$	--	--	1.4	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0V, I_S = 2.0A, dI_F/dt = 100A/\mu s$ (Note4)	--	230	--	ns
$Q_{rr}$	Reverse Recovery Charge		--	1.0	--	$\mu C$

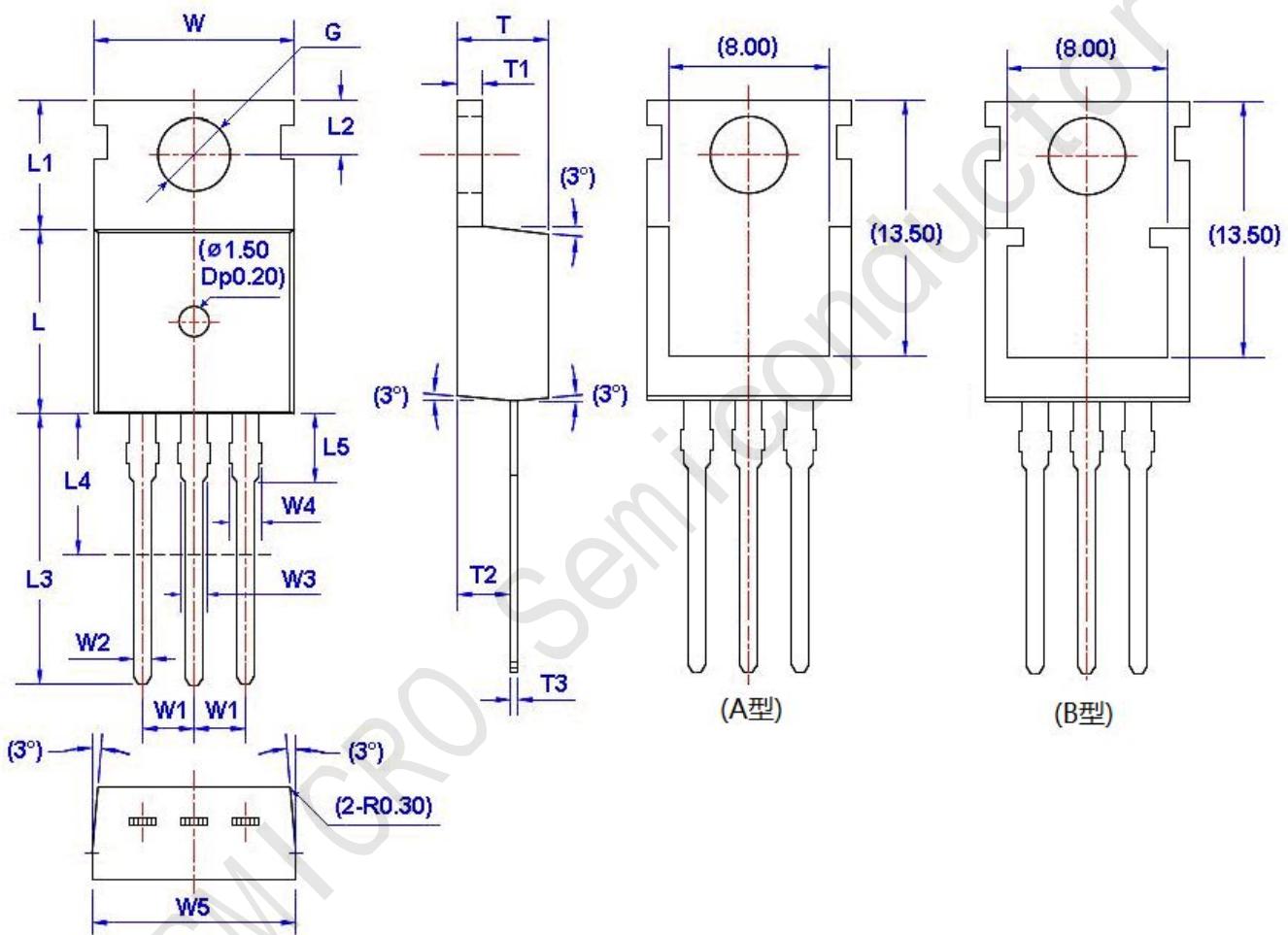
Notes:

- 1、Repetitive Rating:Pulse Width Limited by Maximum Junction Temperature.
- 2、 $L = 56.0mH, I_{AS} = 2.0A, V_{DD} = 50V, R_G = 25\Omega$ , Starting  $T_J = 25^{\circ}C$ .
- 3、 $I_{SD} \leq 2.0A, dI/dt \leq 200A/\mu s, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^{\circ}C$ .
- 4、Pulse Test : Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
- 5、Essentially Independent of Operating Temperature.

**On-Region Characteristics**

**Transfer Characteristics**

**On-Resistance Variation vs. Drain Current and Gate Voltage**

**Capacitance Characteristics**

**Body Diode Forward Voltage Variation vs. Source Current and Temperature**

**Gate Charge Characteristics**


**Breakdown Voltage Variation  
vs. Temperature**

**On-Resistance Variation  
vs. Temperature**

**Maximum Safe Operating Area**

**Maximum Drain Current  
Vs. Case Temperature**


## TO-220 Package Dimensions



Unit: mm

Symbol	Size		Symbol	Size		Symbol	Size		Symbol	Size	
	Min	Max		Min	Max		Min	Max		Min	Max
W	9.66	10.28	W5	9.80	10.20	L4**	6.20	6.60	T3	0.45	0.60
W1	2.54 (TYP)		L	9.00	9.40	L5	2.79	3.30	G(Φ)	3.50	3.70
W2	0.70	0.95	L1	6.40	6.80	T	4.30	4.70			
W3	1.17	1.37	L2	2.70	2.90	T1	1.15	1.40			
W4*	1.32	1.72	L3	12.70	14.27	T2	2.20	2.60			